

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1.(currently amended) A method to dissipate heat generated by a coil located within a micro-structure, that is on a substrate, comprising:

forming a thermally conductive pedestal that extends upwards from said substrate; and

forming a layer of ~~thermally conductive material that~~ thermally connects said pedestal to said coil to said substrate through said pedestal.

2.(previously presented) The method of claim 1 wherein said layer of thermally conductive material and said conductive pedestal have a thermal conductivity between 100 and 400 W/m.K.

3. (currently amended) The method of claim 1 wherein said layer of thermally conductive material is selected from the group consisting of copper, tungsten, molybdenum, silicon, ruthenium, rhodium, and iridium, ~~and all alloys limited to these elements.~~

4. (previously presented) The method of claim 1 wherein said layer of thermally conductive material has a thickness between 1 and 2.5 microns.
5. (previously presented) The method of claim 1 wherein said pedestal has a cross-sectional area that is between 10,000 and 15,000 sq. microns.
6. (previously presented) The method of claim 1 wherein said coil generates heat at a rate between 4 and 15 milliwatts.

7-24. Canceled

25. (currently amended) A heat extractor for a micro-structure that includes a coil and a substrate, comprising:

a thermally conductive pedestal that extends upwards from contact with said substrate; and

a layer that [[of]] thermally conductive material that connects said pedestal to said coil.

26. (previously presented) The heat extractor described in claim 25 wherein said layer of thermally conductive material and said conductive pedestal have a thermal conductivity between 100 and 400 W/m.K.

27. (currently amended) The heat extractor described in claim 25 wherein said layer of thermally conductive material is selected from the group consisting of copper, tungsten, molybdenum, silicon, ruthenium, rhodium, and iridium, ~~and all alloys limited to these elements.~~

28. (previously presented) The heat extractor described in claim 25 wherein said layer of thermally conductive material has a thickness between 1 and 2.5 microns.

29. (previously presented) The heat extractor described in claim 25 wherein said pedestal has a cross-sectional area that is between 10,000 and 15,000 sq. microns.